

MJD340 (NPN) MJD350 (PNP)

High Voltage Power Transistors

DPAK For Surface Mount Applications

Designed for line operated audio output amplifier, switchmode power supply drivers and other switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular MJE340 and MJE350
- 300 V (Min) – $V_{CEO(sus)}$
- 0.5 A Rated Collector Current
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V
Machine Model, C > 400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	300	Vdc
Collector-Base Voltage	V_{CB}	300	Vdc
Emitter-Base Voltage	V_{EB}	3	Vdc
Collector Current – Continuous – Peak	I_C	0.5 0.75	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	15 0.12	W W/ $^\circ\text{C}$
Total Power Dissipation (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.56 0.012	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.33	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Leading Temperature for Soldering Purpose	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

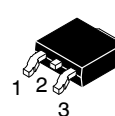
1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



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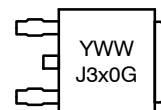
<http://onsemi.com>

**SILICON
POWER TRANSISTORS
0.5 AMPERE
300 VOLTS, 15 WATTS**



**DPAK
CASE 369C
STYLE 1**

MARKING DIAGRAM



Y = Year
WW = Work Week
J3x0 = Device Code
x = 4 or 5
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage (Note 2) ($I_C = 1\text{ mA}$, $I_B = 0$)	$V_{CEO(sus)}$	300	-	V
Collector Cutoff Current ($V_{CB} = 300\text{ V}$, $I_E = 0$)	I_{CEO}	-	0.1	mA
Emitter Cutoff Current ($V_{BE} = 3\text{ V}$, $I_C = 0$)	I_{EBO}	-	0.1	mA

ON CHARACTERISTICS (Note 2)

DC Current Gain ($I_C = 50\text{ mA}$, $V_{CE} = 10\text{ V}$)	h_{FE}	30	240	-
Collector-Emitter Saturation Voltage ($I_C = 100\text{ mA}$, $I_B = 10\text{ mA}$)	$V_{CE(sat)}$	-	1	V
Base-Emitter On Voltage ($I_C = 1\text{ A}$, $V_{CE} = 10\text{ V}$)	$V_{BE(on)}$	-	1.5	V

DYNAMIC CHARACTERISTICS

Current Gain — Bandwidth Product ($I_C = 50\text{ mA}$, $V_{CE} = 10\text{ V}$, $f = 10\text{ MHz}$)	f_T	10	-	MHz
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2. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS

MJD340

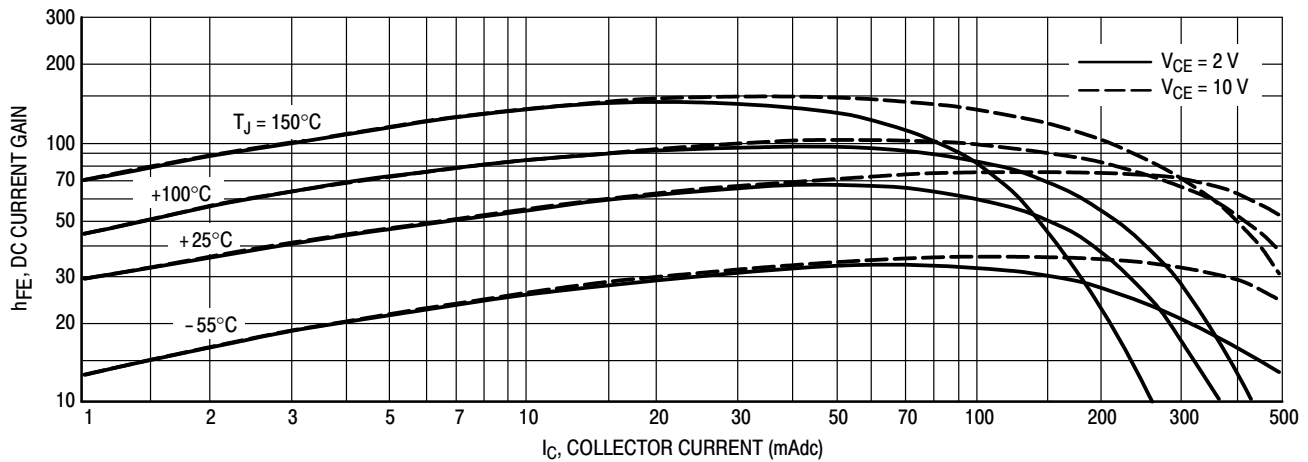


Figure 1. DC Current Gain

MJD340 (NPN) MJD350 (PNP)

MJD340

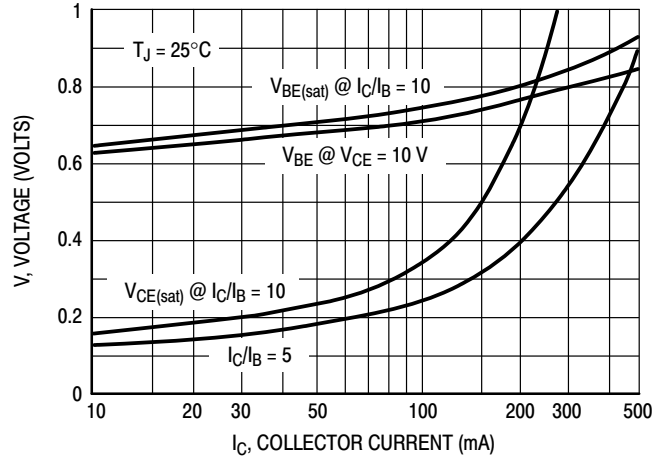


Figure 2. "On" Voltages

MJD350

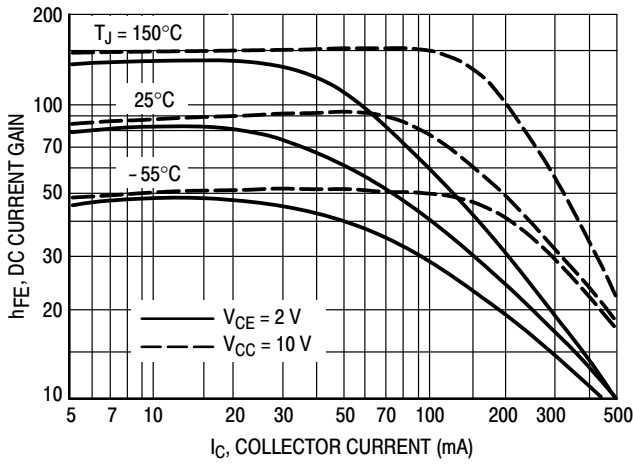


Figure 3. DC Current Gain

MJD350

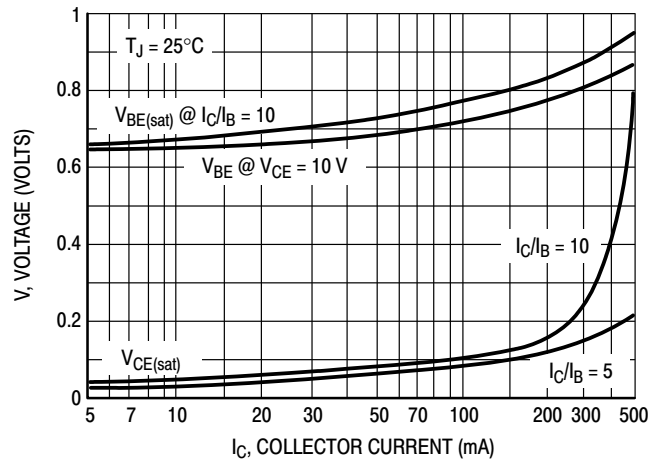


Figure 4. "On" Voltages

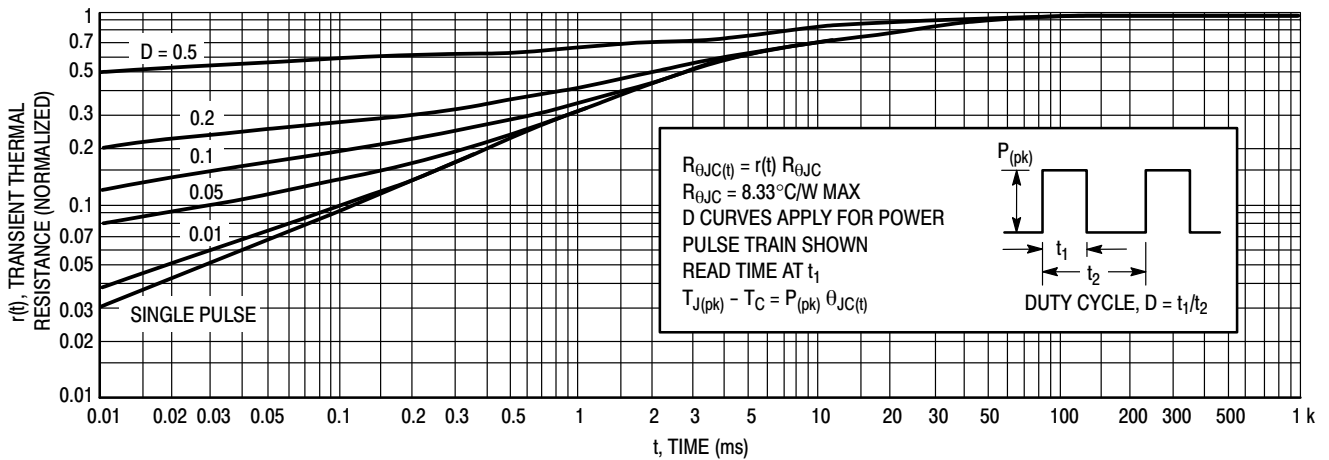


Figure 5. Thermal Response

MJD340 (NPN) MJD350 (PNP)

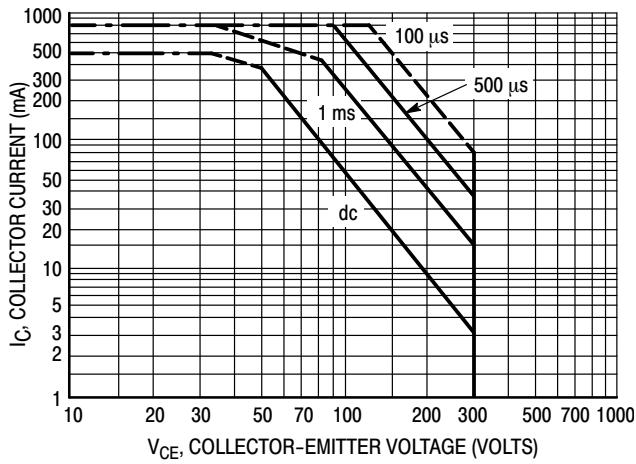


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

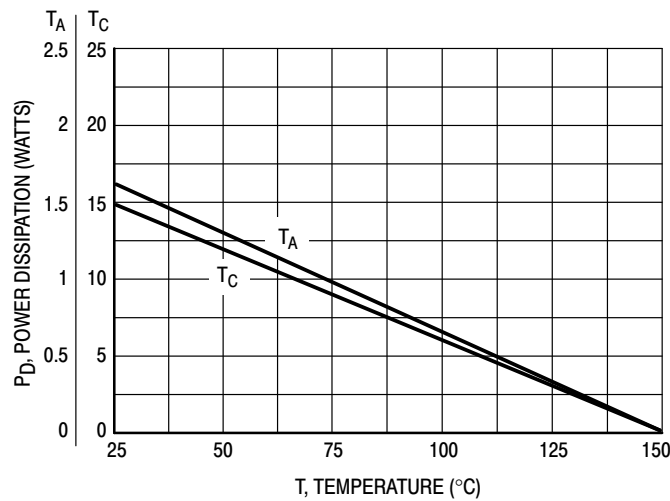


Figure 7. Power Derating

ORDERING INFORMATION

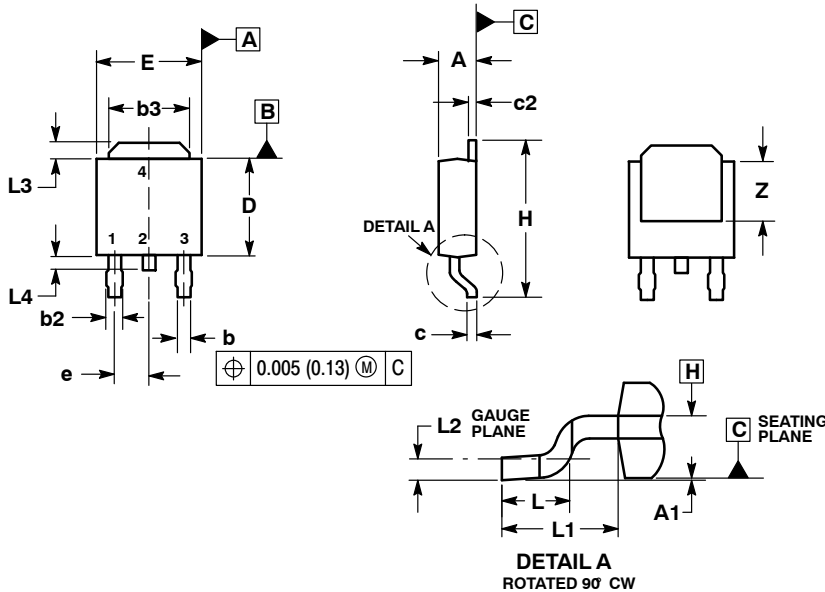
Device	Package	Shipping [†]
MJD340	DPAK	75 Units / Rail
MJD340G	DPAK (Pb-Free)	
MJD340RL	DPAK	1800 / Tape & Reel
MJD340RLG	DPAK (Pb-Free)	
MJD340T4	DPAK	2500 / Tape & Reel
MJD340T4G	DPAK (Pb-Free)	
MJD350	DPAK	75 Units / Rail
MJD350G	DPAK (Pb-Free)	
MJD350T4	DPAK	2500 / Tape & Reel
MJD350T4G	DPAK (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

DKPAK
CASE 369C-01
ISSUE D

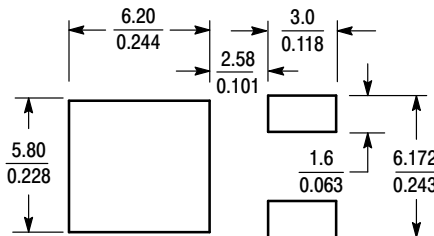


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



SCALE 3:1 (mm/inches)

STYLE 1:

- PIN 1. BASE
- COLLECTOR
- EMITTER
- COLLECTOR

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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